

Abstract

The present invention provides a method and apparatus to package and electrically connect a microdisplay that includes a cavity package design. This cavity package design improves the packaging of the microdisplay by using a low number of parts, less processing, and is independent of the customer's interconnect. Structurally, the invention is a unified part, forming a cavity for insertion of a microdisplay cell. Additionally, the cavity package incorporates a variety of test features for ease of testing. Also, the cavity package is a small size and includes multiple mounting options allowing flexibility to customer changes and multiple configurations.